Multi-Row Board-to-Board Connector

Multi-Row Board-to-Board Connector modules provide highly efficient, configurable pin-count, snap-in stackable interfaces for creating highly reliable and low-cost multi-board assemblies.

ENNOVI™

HIGHLY CONFIGURABLE

The snap-in biscuit design supports a wide range of customization for various pin configurations, multiple circuits and board spacing options.

PLUGGABLE AND RELIABLE

The multi-row modules provide very low contact resistance levels (<1mΩ) and compliance with automotive standards IEC60352-5 and IPC-9797.

HIGH PERFORMANCE MATERIALS

Provides high amperage interfaces with environmental resistance to humidity, temperature cycling, vibration, mechanical shock and more.

APPLICATIONS

Sensors, actuators, electronic control units (ECUs), steering systems, infotainment systems, on-board chargers, charging systems in:

+ Electric vehicles
+ Commercial transportation
+ Personal mobility

Control units and a wide range of multi-PCB stacked assemblies:

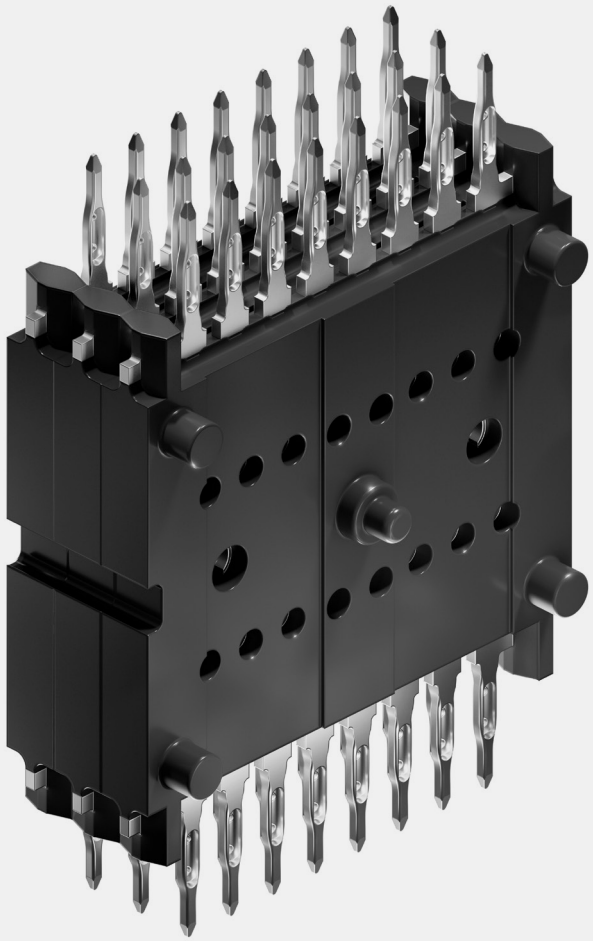
+ Industrial
+ Medical

SIGNAL INTERFACE

+ Robust, solder-free connection with the 0.4 miniPLX™ Press-Fit pins.
+ Current rating: 3 Amps/pin.
+ Option for IndiCoat™: whisker mitigation plating technology developed by ENNOVI.
+ High data rate capability, up to 12 GHz / 24 Gbps.
+ Automotive-approved solution; meets IEC60352-5 and IPC-9797 standards.

CONFIGURABLE SOLUTION

+ Design flexibility with ENNOVI's snap-in biscuit design.
+ High density - 1.8mm pin-to-pin spacing with 2mm row-to-row spacing.
+ 7mm to 30mm board spacing.
+ 4 to 30 circuits per row.
+ 1 to 6 rows.



TECHNICAL INFO

PARAMETER	VALUE/RANGE
Relative humidity (RH)	80% to 100%, 8-hour cycling
Working temperature range	-40°C to +150°C
Mechanical shock	35g for 5 to 10ms across 10 axes
Vibration	8 hour per axis
Voltage	500V DC ±10%
Insulation resistance	≥100 MΩ